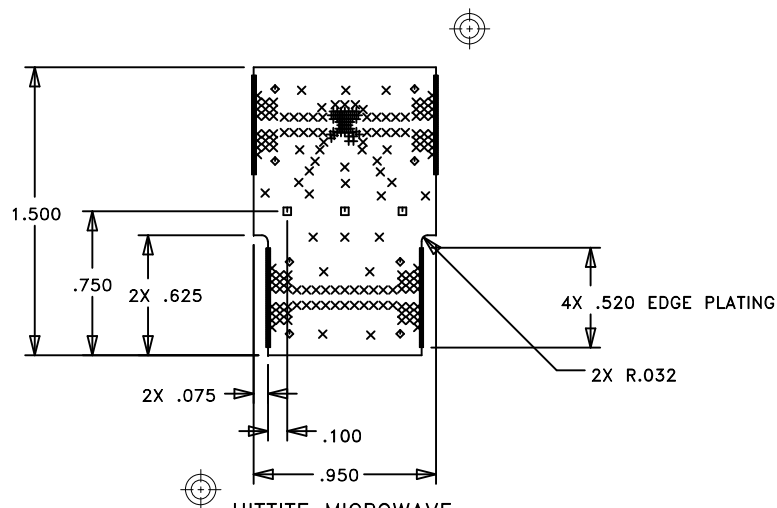


DO NOT SCALE PRINT

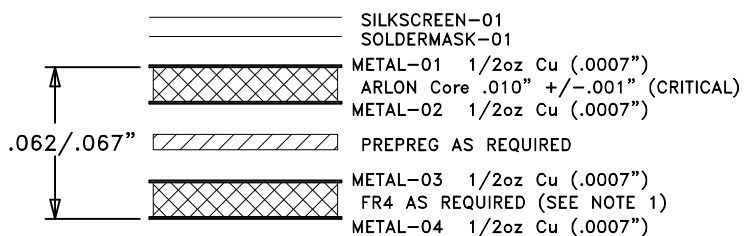
REVISION				
ZONE	LTR	DESCRIPTION	DATE	APPROVED
	1	ENGINEERING RELEASE	06/01/09	V. LY



HITTITE MICROWAVE
PCB #126357-1
DRILL DRAWING

SIZE	QTY	SYM	PLATED	TOL
10	48	+	YES	+/-3
14	155	X	YES	+/-3
43	3	□	YES	+/-3
78	8	◇	YES	+/-3

LAYER	DESCRIPTION
1	RF/GND PLANE
2	GND PLANE
3	GND PLANE
4	BOTTOM GND PLANE



LAYER STACKUP

PROPRIETARY TO HITTITE MICROWAVE CORPORATION

UNLESS OTHERWISE SPECIFIED:	
DIMENSIONS ARE IN INCHES (MM)	
DRAWING PRACTICES PER MIL-STD-100	
TOLERANCES:	
.XX	+/- 0.010
.XXX	+/- 0.005
.XXXX	+/- 0.002
ANGLES	+/- .5 DEG

DWN BY:	V. LY	06/01/2009
ENGINEER:	J. SCORSE	06/02/2009



HITTITE MICROWAVE CORPORATION
20 Alpha Road Chelmsford, MA 01824

TITLE
PCB, EVAL,
HMC772LC4

SIZE	CODE ID NO.	DRAWING NO.	REV
A	1CN88	126357	1
SCALE:		WT	SHEET 1 of 1

NOTES:
UNLESS OTHERWISE SPECIFIED:

1. MATERIAL: MULTILAYER. OVERALL STACKUP AS SHOWN. TYPE ROGERS 4350 OR ARLON 25FR, HALF OUNCE COPPER BOTH SIDES, FR4 TO BE USED AS FILLER TO MEET CRITICAL OVERALL THICKNESS.
2. FINISH: GOLD PLATE PER ASTM B-488, TYPE III, CODE A, 8 TO 40 MICROINCHES, OVER NICKEL PER QQ-N-290, 100 MICROINCHES MINIMUM.
3. PLATED THRU HOLES: .001" MINIMUM WALL THICKNESS.
4. HOLE SIZES AND POSITIONS PER ARTWORK AND/OR DRILL FILE.
5. ALL HOLES TO BE LOCATED WITHIN ± 0.003 " OF THE CENTER OF THE PAD OR OTHER TRUE POSITION.
6. FRONT TO BACK REGISTRATION ± 0.003 " MAX.
7. BOARD WARPAGE: $< .010$ " PER LINEAR INCH.
8. SILKSCREEN TOPSIDE ONLY WITH WHITE EPOXY INK.
9. PLATING THICKNESS $.002 \pm .0005$ FOR METAL-01 AND METAL-04.
10. SOLDERMASK: LPI SOLDERMASK TOP SIDE. COLOR: GREEN REGISTRATION: ± 0.004 MAX.
11. REMOVE METAL BURRS FROM EDGE OF PCB AFTER PANEL SEPARATION.
12. ARTWORK IS 1:1. VENDOR TO ADJUST FOR ETCH FACTOR.
13. "SIZE" IN DRILL LEGEND IS IN MILS AND REFERS TO FINISHED HOLE SIZE.
14. MANUFACTURE PER IPC-600 CLASS 2.

SPECIAL REQUIREMENTS:

15. METAL-01 CRITICAL LINE WIDTH = $.018 \pm .001$ " ADJUST PROCESS TO ACHIEVE WIDTH.
16. EDGE PLATING MUST CONNECT ALL FOUR METAL LAYERS.
17. ALL .010" SIZE VIAS TO BE FILLED WITH NON-CONDUCTIVE VIA FILL AND OVERPLATED WITH Cu BOTH SIDES.